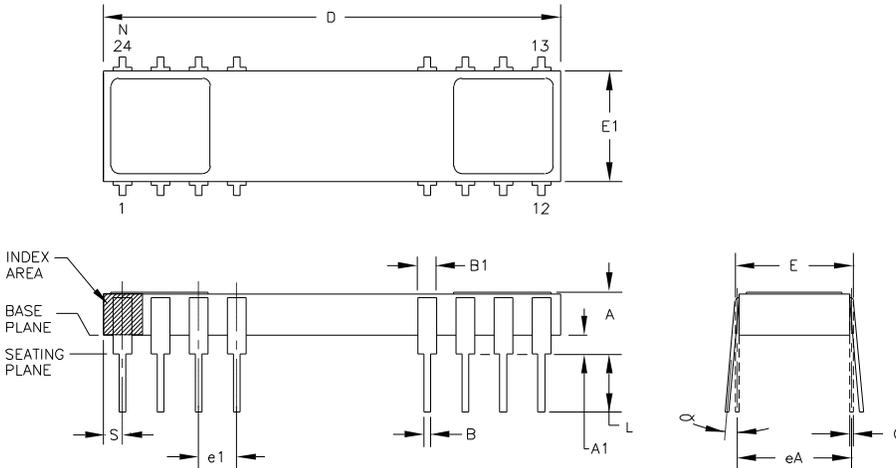


Package Number 225 - 24-Lead Side Braze DIP, .300 Wide, ISO Package



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	.140	.185	3.56	4.70									
A1	.040	.060	1.02	1.52									
B	.016	.020	0.41	0.51	5								
B1	.045	.055	1.14	1.40	5								
C	.009	.012	0.23	0.30									
D	1.188	1.212	30.18	30.78									
E	.300	.320	7.62	8.13									
E1	.280	.300	7.11	7.62	6								
e1	.100 TYP.		2.54 TYP.		2								
eA	.300 TYP.		7.62 TYP.		2								
L	.125	.180	3.18	4.57									
N	16		16		4								
S	.035	.065	0.89	1.65									
α	0°	15°	0°	15°	3								

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1982.
 2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
 3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
 4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE (A1 = 0), TERMINAL LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ225 | REV.: E
 JEDEC NUMBER: NONE



PACKAGE DRAWING

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